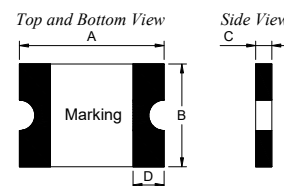


1、Physical Dimensions(size of 2920)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
LSMD100/60	6.73	7.98	4.80	5.44	0.95	1.85	0.30	T100



2、Electrical Characteristics

Part Number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} (Max time to trip)		Pd _{typ} (W)	R _{min} (Ω)	R _{1max} (Ω)
					Current(A)	Time(S)			
LSMD100/60	1.00	2.00	60	100	8.0	0.5	1.5	0.090	0.410

I_H: Holding Current: maximum current at which the device will not trip in 25°C still air.

I_T: Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

T_{trip}: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25°C.

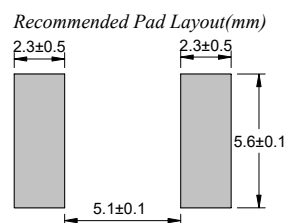
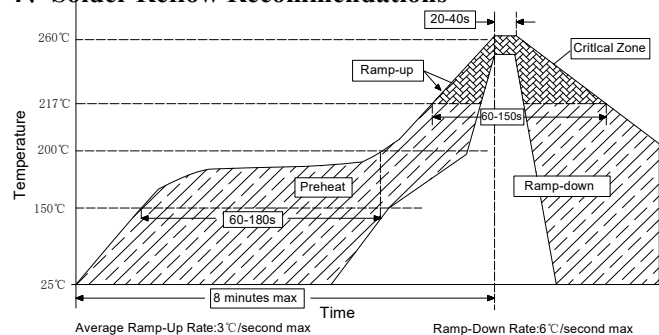
R_{1max}: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

3、Thermal Derating

LSMD100/60	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	1.66	1.47	1.29	1.00	0.91	0.83	0.73	0.64	0.50
Trip Current(A)	3.32	2.94	2.58	2.00	1.82	1.66	1.46	1.28	1.00

4、Solder Reflow Recommendations



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、Package Information

Packing quantity: 1000PCS/Reel

Note: Reel packaging per EIA-481-2 standard